

Monolithic Amplifier

ERA-4XSM+ ERA-4XSM

50Ω, Broadband, DC to 4 GHz

Features

- wide bandwidth, DC-4 GHz
- gain, 14.7 dB typ. at 100 MHz
- high dynamic range, 4.2 dB NF, 35 dBm IP3
- low thermal resistance for high reliability
- supply voltage transient protection
- patent pending

Applications

- cellular
- PCS
- communication receivers & transmitters



CASE STYLE : WW107

+ RoHS compliant in accordance with EU Directive (2002/95/EC)

The +suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications.

Electrical Specifications @ 25°C

MODEL NO.	FREQ.* (GHz)	GAIN, dB Typical						MAXIMUM POWER (dBm) @1GHz			DYNAMIC RANGE @1GHz		VSWR (:1) Typ.				MAXIMUM RATING**		DC OPERATING POWER @ Pin 3***			THERMAL RESISTANCE θjc, typ. °C/W	PRICE \$ Qty. (25)	
		over frequency, GHz					Min. @ 2 GHz	Output (1dB Comp.) Typ.	Input (no dmg.) Min.	NF (dB) Typ.	IP3 (dBm) Typ.	In DC-3 GHz	Out 3-4 GHz	DC-2 GHz	2-4 GHz	I mA	P mW	Current (mA)	Volt Typ	Min	Max			
ERA-4XSM(+)	DC-4	14.7	14.2	13.5	12.0	11.8	12	17.0	15	20	4.2	35	1.2	1.2	1.2	1.4	100	650	65	4.5	4.2	5.5	196	1.69

* Low frequency cutoff determined by external coupling capacitors.
 ** Permanent damage may occur if any of these limits are exceeded. These ratings are not intended for continuous normal operation.
 ***Reliability predictions and normal operating conditions are applicable at current specified.

Maximum Ratings

Operating Temperature -45°C to 85°C
 Storage Temperature -65°C to 150°C

Model Identification

Model	Marking†
ERA-4XSM(+)	4X

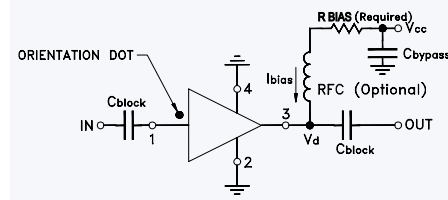
† Prefix letter (optional) designates assembly location. Suffix letters (optional) are for wafer identification.

Pin Configuration

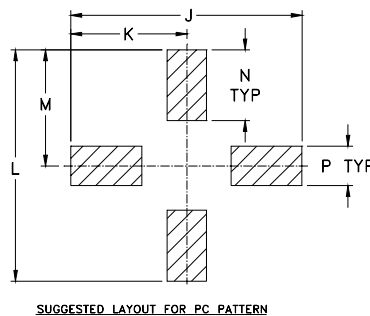
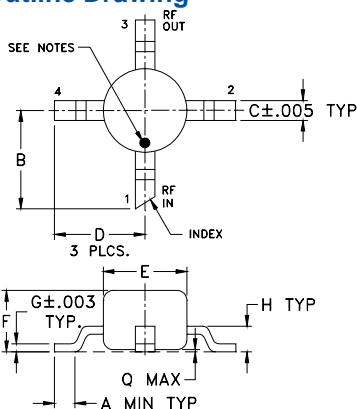
RF IN	1
RF OUT	3
DC	3
GROUND	2,4

R BIAS *1% Resistor Values ERA-4XSM(+)	
Vcc	7
	8
	9
	10
	11
	12
	13
	14
	15
	16
	17
	18
	19
	20

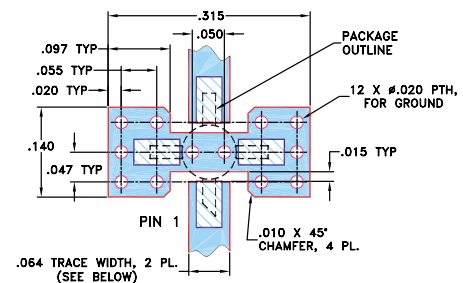
Typical Biasing Configuration



Outline Drawing



Suggested PCB Layout (PL-075)



NOTES:

1. TRACE WIDTH IS SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS .030" ± .002"; COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
3. IF PCB DESIGN RULES ALLOW, PLACE GROUND VIAS UNDER THE LAND PATTERN FOR BETTER RF PERFORMANCE. OTHERWISE PLACE GROUND VIAS AS CLOSE TO LAND PATTERN AS POSSIBLE.

- DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER)
- DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

Outline Dimensions (inch/mm)

A	B	C	D	E	F	G	H	J	K	L	M	N	P	Q	wt. grams
.012	.10	.020	.092	.085	.060	.007	.026	.235	.118	.235	.118	.072	.040	.020	
.30	2.54	.51	2.34	2.16	1.52	.18	.66	5.97	3.00	5.97	3.00	1.83	1.02	0.51	.015



